L Number	Hits	Search Text	DB	Time stamp
1	112	(((dielectric insulat$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat$3 solution))) and ((dielectric insulat$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat$3 solution)))	USPAT; US-PGPUB	2004/09/29 18:19
2	40	((((dielectric insulat$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat$3 solution))) and ((dielectric insulat$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat$3 solution)))) and (argon Ar)	USPAT; US-PGPUB	2004/09/29 18:19
3	10	(((dielectric insulat$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat$3 solution))) and ((dielectric insulat$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat$3 solution)))	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:19
5	0	((((dielectric insulat$3) and (hydrogen H2 "H.sub.2")) and (wet near10 (treat$3 solution))) and ((dielectric insulat$3) near100 (hydrogen H2 "H.sub.2") near100 (wet near10 (treat$3 solution)))) and (argon Ar)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:19
6	10279	(ILD (inter near5 dielectric) IMD)	USPAT; US-PGPUB	2004/09/29 18:39
7	3316	((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")	USPAT; US-PGPUB	2004/09/29 18:39
8	2351	(((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)	USPAT; US-PGPUB	2004/09/29 18:39
9	1440	((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean$3 treat$3)	USPAT; US-PGPUB	2004/09/29 18:21
10	942	(((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean$3 treat$3)) and plasma	USPAT; US-PGPUB	2004/09/29 18:21
11	523	((((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean$3 treat$3)) and plasma) and (argon "Ar")	USPAT; US-PGPUB	2004/09/29 18:22
12	332	(((((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean$3 treat$3)) and plasma) and (argon "Ar")) and (resist PR photoresist)	USPAT; US-PGPUB	2004/09/29 18:22
13	327	((((((((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)) and (clean$3 treat$3)) and plasma) and (argon "Ar")) and (resist PR photoresist)) and (etch$3 pattern$3)	USPAT; US-PGPUB	2004/09/29 18:23
14	2414	(ILD (inter near5 dielectric) IMD)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:39
15	86	((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:39
16	14	(((ILD (inter near5 dielectric) IMD)) and (hydrogen "H.sub.2")) and (wet solution)	EPO; JPO; DERWENT; IBM_TDB	2004/09/29 18:40